

Portable Equipment Application. Notebook Application.

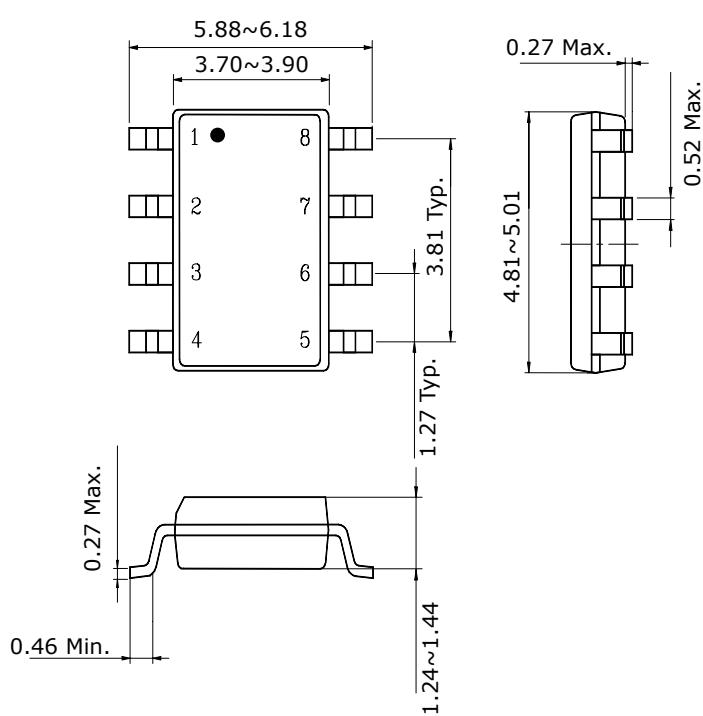
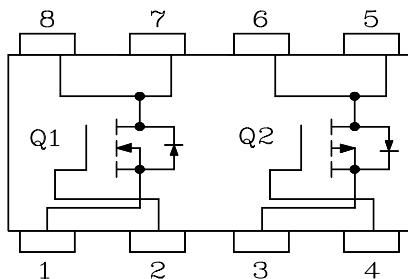
Features

- Low $V_{GS(th)}$: $V_{GS(th)}=1.0\sim3.0V$
- Small footprint due to small package
- Low $R_{DS(on)}$: Low $R_{DS(on)}=N\text{-ch}:24m\Omega$, $P\text{-ch}:66m\Omega$

Ordering Information

Type NO.	Marking	Package Code
SUF2001	SUF2001	SOP-8

Outline Dimensions

unit : mm

Block Diagram

PIN Connections

1. Source 1
2. Gate 1
3. Source 2
4. Gate 2
5. Drain 2
6. Drain 2
7. Drain 1
8. Drain 1

Absolute maximum ratings

(Ta=25°C)

Characteristic	Symbol	Rating		Unit
		N-Ch	P-Ch	
Drain-source voltage	V _{DSS}	30	-30	V
Gate-source voltage	V _{GSS}	±20		V
Drain current (DC)	I _D	5.8	-5.3	A
Drain current (Pulsed) *	I _{DP}	23.2	-21.2	A
Total Power dissipation **	P _D	2.0		W
Avalanche current (Single)	I _{AS}	(2)5.8	(6)-5.3	A
Single pulsed avalanche energy	E _{AS}	(2)72	(6)33	mJ
Avalanche current (Repetitive) ①	I _{AR}	5.8	-5.3	A
Repetitive avalanche energy ①	E _{AR}	3.4	1.6	mJ
Junction temperature	T _J	150		°C
Storage temperature range	T _{sta}	-55~150		

* Limited by maximum junction temperature

** Device mounted on a glass-epoxy board

Characteristic	Symbol	Typ.	Max	Unit
Thermal resistance	R _{th(J-a)}	62.5	-	°C/W

N-CH Electrical Characteristics

(Ta=25°C)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV _{DSS}	I _D =250μA, V _{GS} =0	30	-	-	V
Gate threshold voltage	V _{GS(th)}	I _D =250μA, V _{DS} = V _{GS}	1.0	-	3.0	V
Drain-source cut-off current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
Gate leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Drain-source on-resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2.9A	-	24	30	mΩ
		V _{GS} =5.0V, I _D =2.9A	-	28	34	mΩ
Forward transfer conductance ④	g _{fs}	V _{DS} =5V, I _D =5.8A	-	12	-	S
Input capacitance	C _{iss}	V _{GS} =0V, V _{DD} =10V, f=1MHz	-	370	560	pF
Output capacitance	C _{oss}		-	60	90	
Reverse transfer capacitance	C _{rss}		-	36	54	
Turn-on delay time	t _{d(on)}	V _{DD} =15V, I _D =5.8A R _G =10Ω	-	1.2	-	ns
Rise time	t _r		-	1.1	-	
Turn-off delay time	t _{d(off)}		-	2.5	-	
Fall time	t _f		-	1.1	-	
Total gate charge	Q _g	V _{DD} =15V, V _{GS} =5V I _D =5.8A	-	4.2	6.3	nC
Gate-source charge	Q _{gs}		-	0.9	1.4	
Gate-drain charge	Q _{gd}		-	1.4	2.1	

Source-Drain Diode Ratings and Characteristics

(Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current	I _S	Integral reverse diode in the MOSFET	-	-	1.5	A
Source current(Plusd) ①	I _{SM}		-	-	6.0	
Forward voltage ④	V _{SD}	V _{GS} =0V, I _S =1.5A	-	-	1.2	V
Reverse recovery time	t _{rr}	I _s =1.5A di _s /dt=100A/us	-	90	-	ns
Reverse recovery charge	Q _{rr}		-	0.5	-	

Note :

- ① Repetitive Rating : Pulse width limited by maximum junction temperature
- ② L=3.4mH, I_{AS}=5.8A, V_{DD}=15V, R_G=25Ω
- ③ Pulse Test : Pulse Width < 300us, Duty cycle≤ 2%
- ④ Essentially independent of operating temperature

P-CH Electrical Characteristics

(Ta=25°C)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV _{DSS}	I _D =250μA, V _{GS} =0	-30	-	-	V
Gate threshold voltage	V _{GS(th)}	I _D =250μA, V _{DS} =V _{GS}	-1.0	-	-3.0	V
Drain-source cut-off current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	1	μA
Gate leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Drain-source on-resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-2.7A	-	66	72	mΩ
		V _{GS} =-5.0V, I _D =-2.7A	-	77	83	mΩ
Forward transfer conductance ⑧	g _{fs}	V _{DS} =-5V, I _D =-5.3A	-	11	-	S
Input capacitance	C _{iss}	V _{GS} =0V, V _{DD} =-10V, f=1MHz	-	390	590	pF
Output capacitance	C _{oss}		-	97	150	
Reverse transfer capacitance	C _{rss}		-	37	60	
Turn-on delay time	t _{d(on)}	V _{DD} =-15V, I _D =-5.3A R _G =10Ω	-	1.2	-	ns
Rise time	t _r		-	1.1	-	
Turn-off delay time	t _{d(off)}		-	2.5	-	
Fall time	t _f		-	1.1	-	
Total gate charge	Q _g	V _{DD} =-15V, V _{GS} =-5V I _D =-5.3A	-	4.7	7.0	nC
Gate-source charge	Q _{gs}		-	1.4	2.1	
Gate-drain charge	Q _{gd}		-	1.7	2.5	

Source-Drain Diode Ratings and Characteristics

(Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current	I _S	Integral reverse diode in the MOSFET	-	-	-1.5	A
Source current(Plusd) ⑤	I _{SM}		-	-	-6.0	
Forward voltage ⑧	V _{SD}	V _{GS} =0V, I _S =-1.5A	-	-	-1.2	V
Reverse recovery time	t _{rr}	I _s =-1.5A di _S /dt=100A/us	-	90	-	ns
Reverse recovery charge	Q _{rr}		-	0.5	-	uC

Note :

⑤ Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

⑥ L=2.0mH, I_{AS}=-5.0A, V_{DD}=-15V, R_G=25Ω

⑦ Pulse Test : Pulse Width < 300us, Duty cycle≤ 2%

⑧ Essentially independent of operating temperature

N-CH Electrical Characteristic Curves

Fig. 1 I_D - V_{DS}

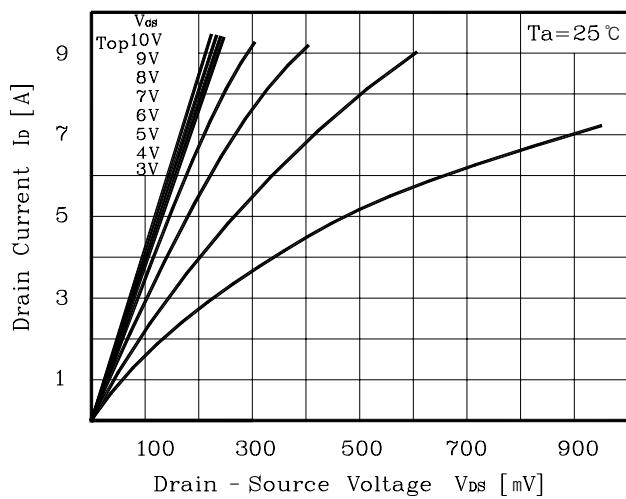


Fig. 2 I_D - V_{GS}

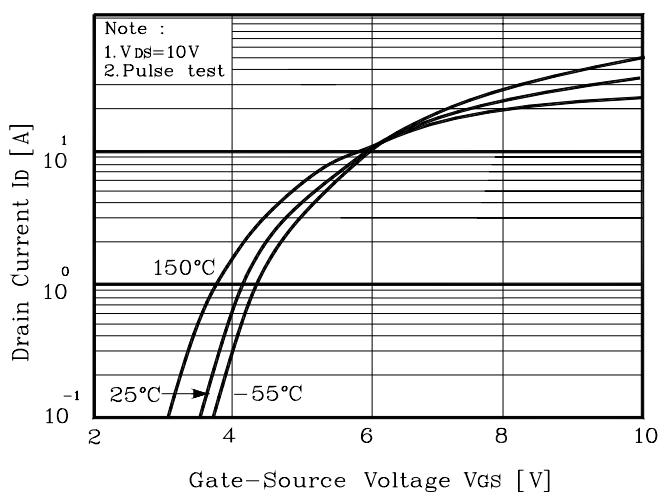


Fig. 3 $R_{DS(on)}$ - I_D

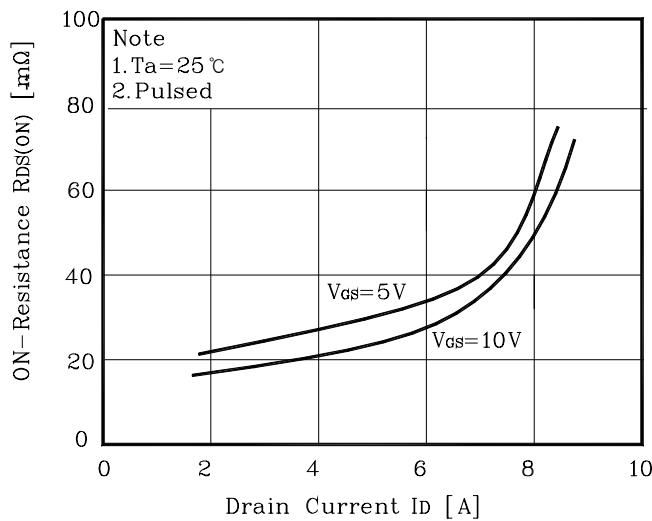


Fig. 4 I_S - V_{SD}

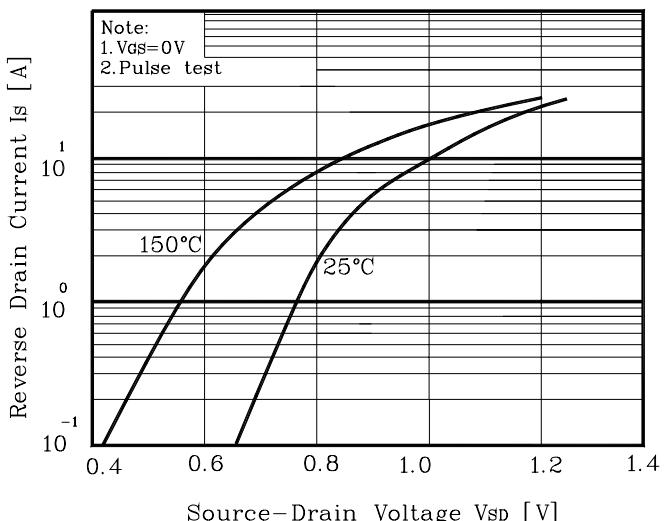


Fig. 5 Capacitance - V_{DS}

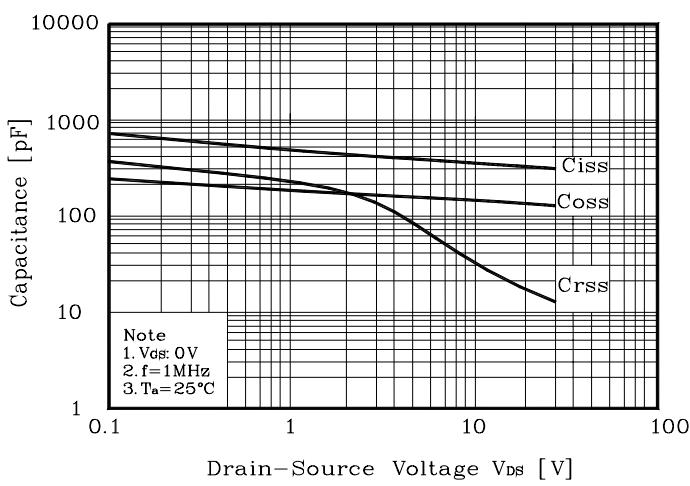


Fig. 6 V_{GS} - Q_G

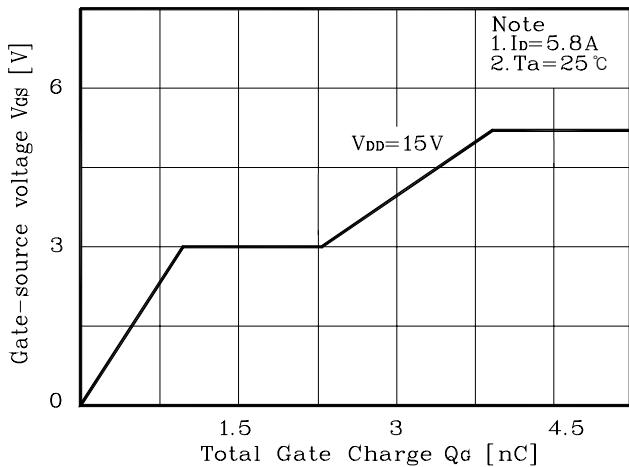


Fig. 7 V_{DSS} - T_J

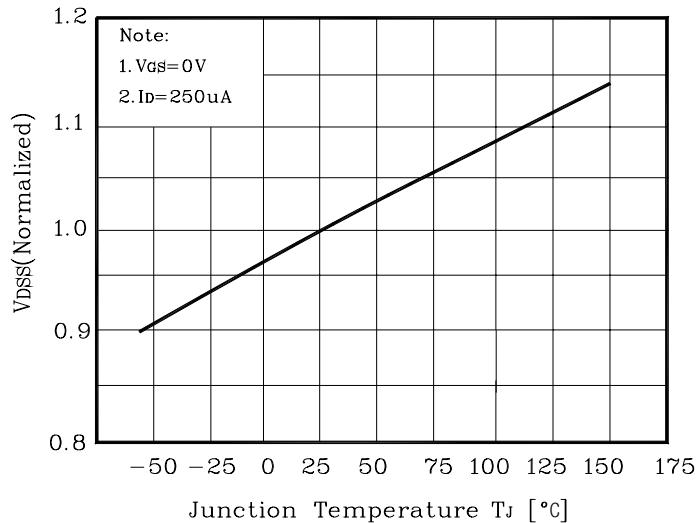


Fig. 8 $R_{DS(on)}$ - T_J

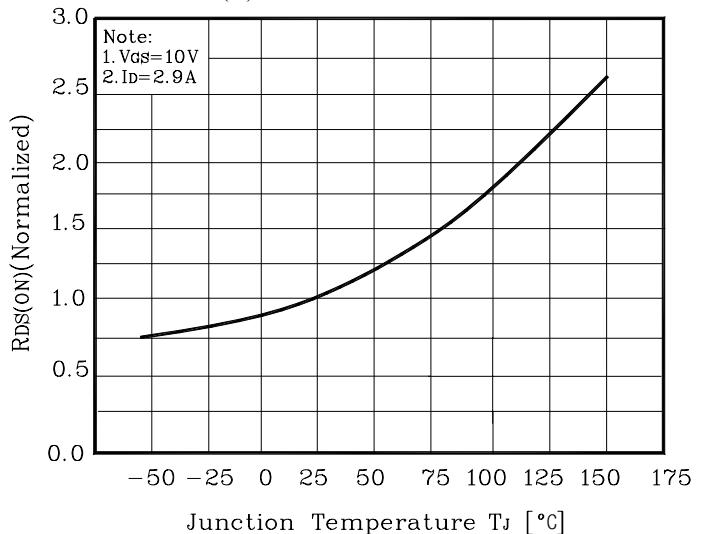


Fig. 9 I_D - T_a

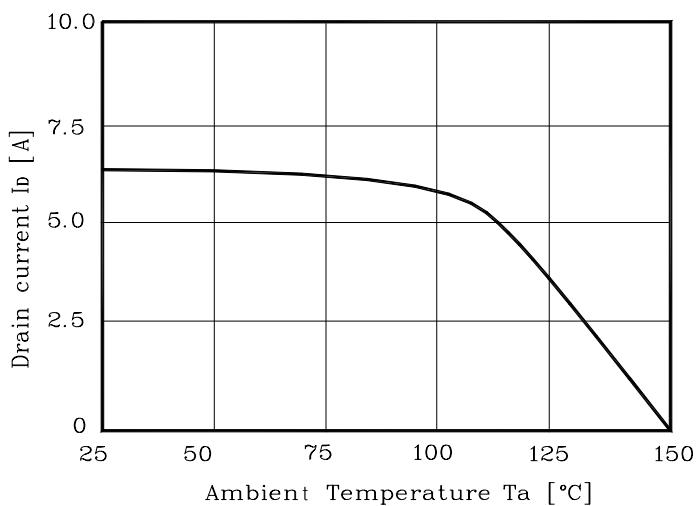


Fig. 10 Safe Operating Area

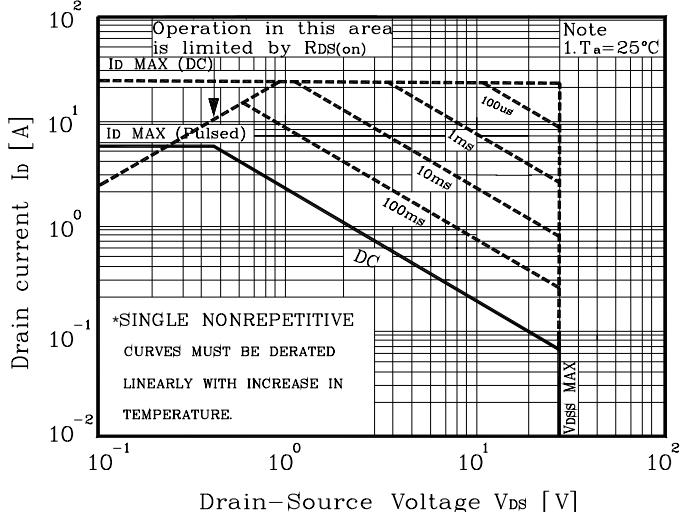


Fig. 11 Gate Charge Test Circuit & Waveform

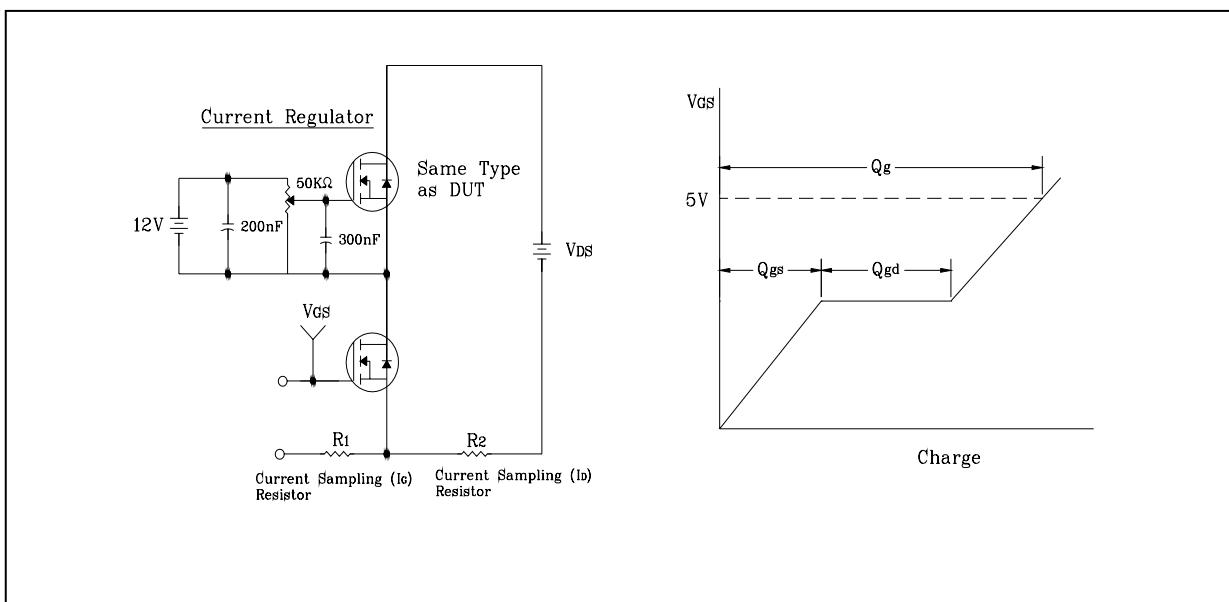


Fig. 12 Resistive Switching Test Circuit & Waveform

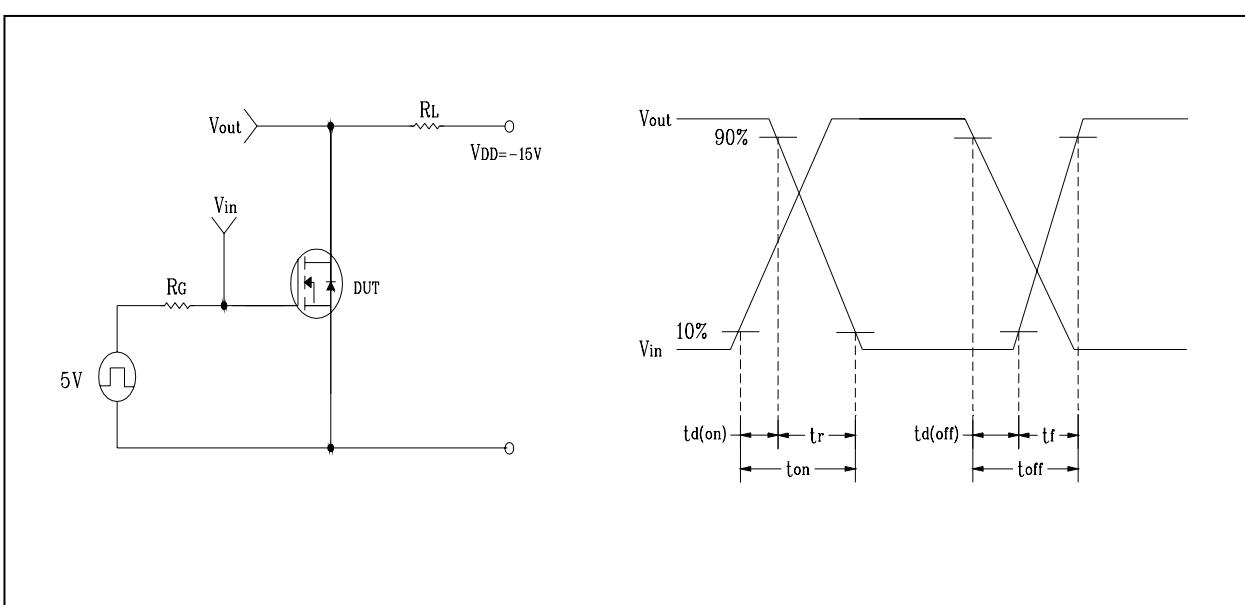


Fig. 13 E_{AS} Test Circuit & Waveform

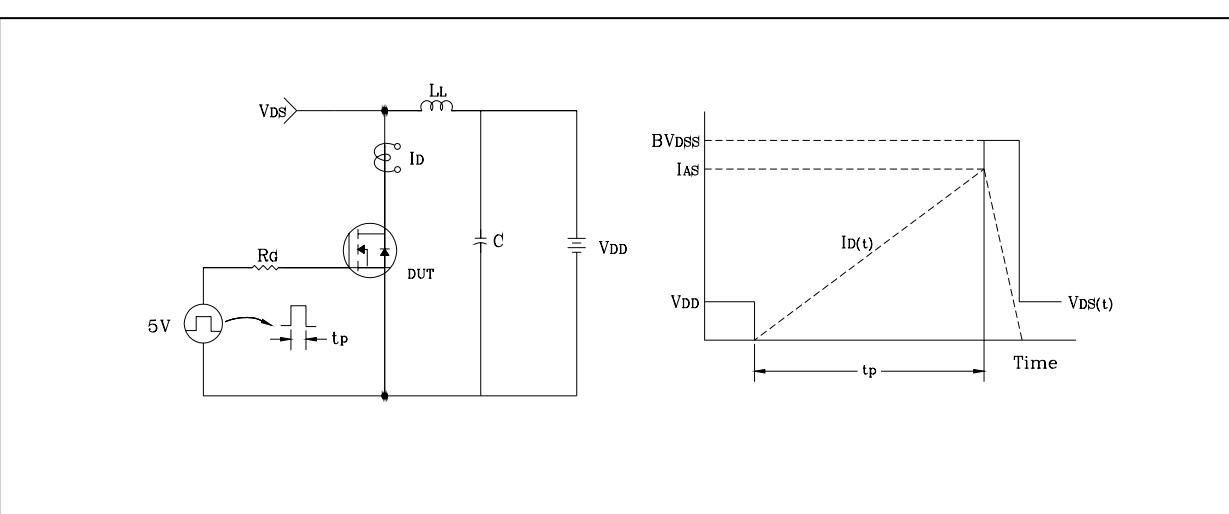
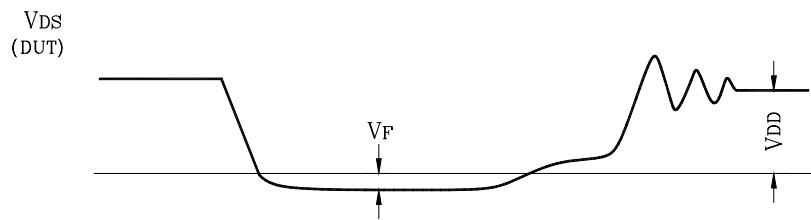
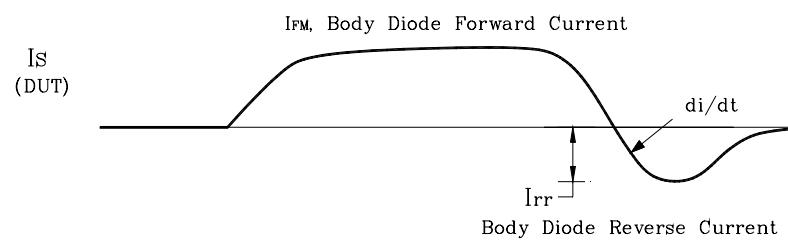
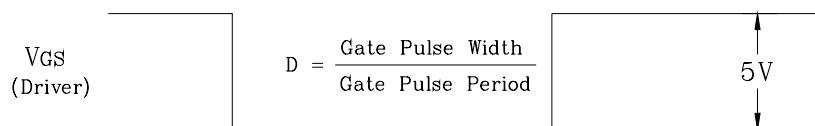
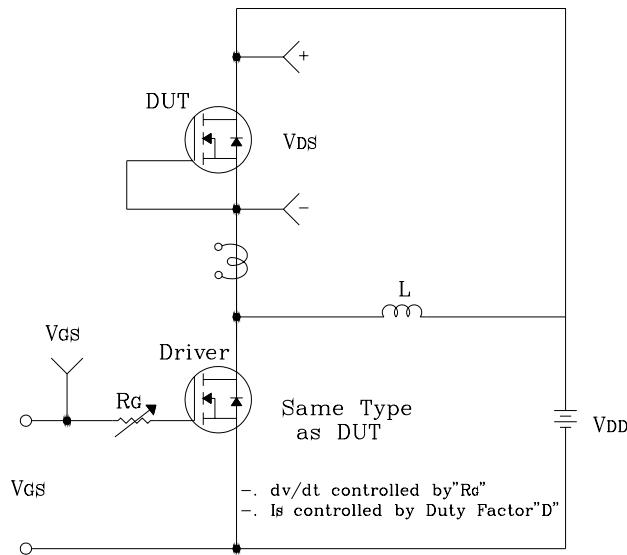


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform



P-CH Electrical Characteristic Curves

Fig. 1 I_D - V_{DS}

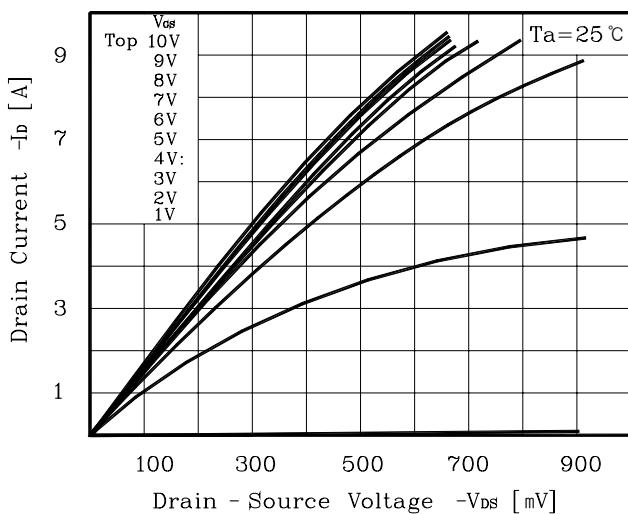


Fig. 3 $R_{DS(on)}$ - I_D

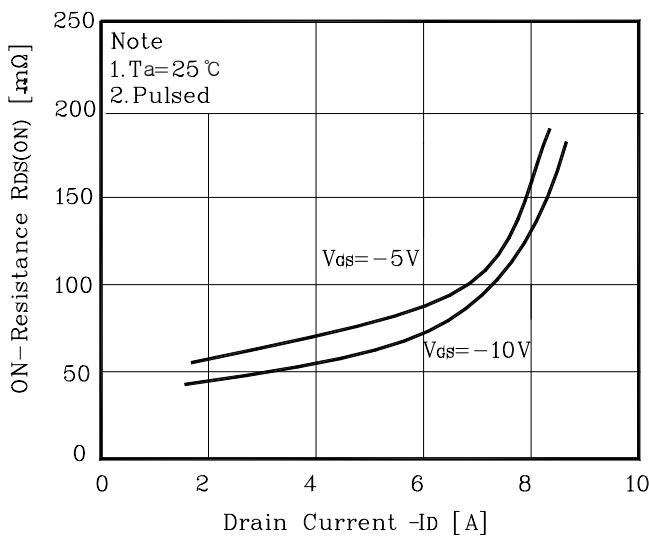


Fig. 5 Capacitance - V_{DS}

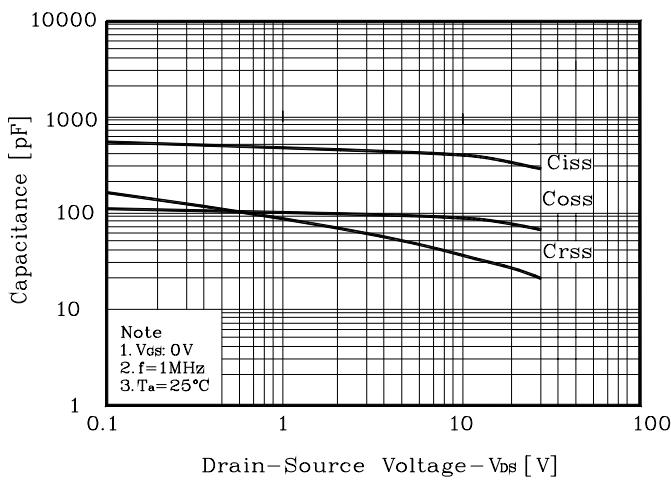


Fig. 2 I_D - V_{GS}

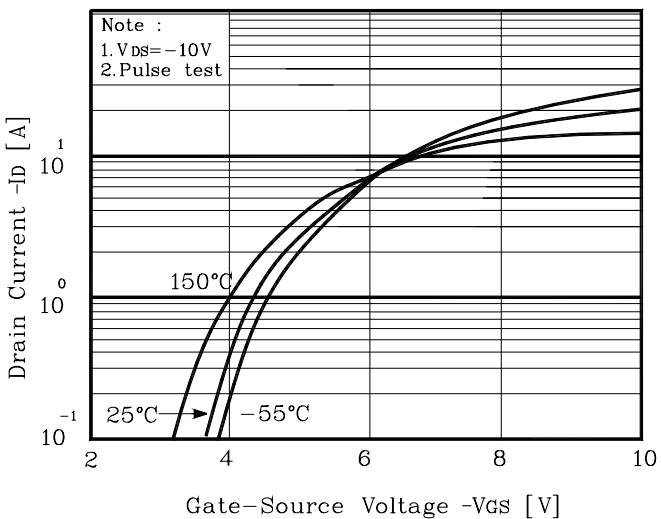


Fig. 4 I_S - V_{SD}

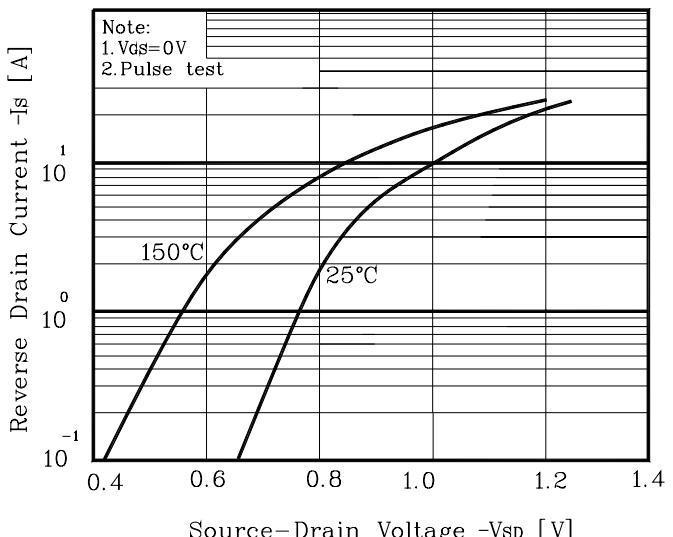


Fig. 6 V_{GS} - Q_G

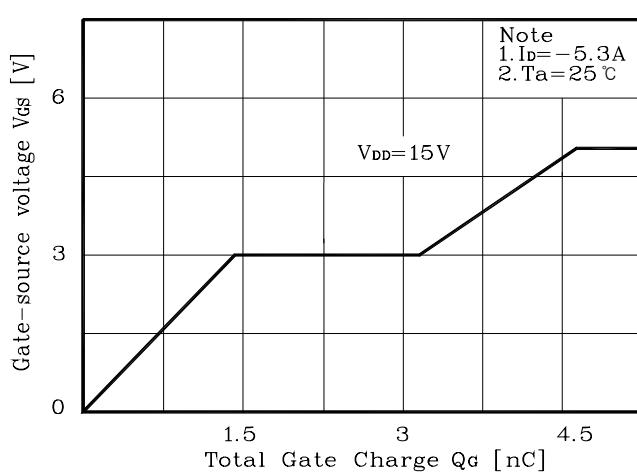


Fig. 7 V_{DSS} - T_J

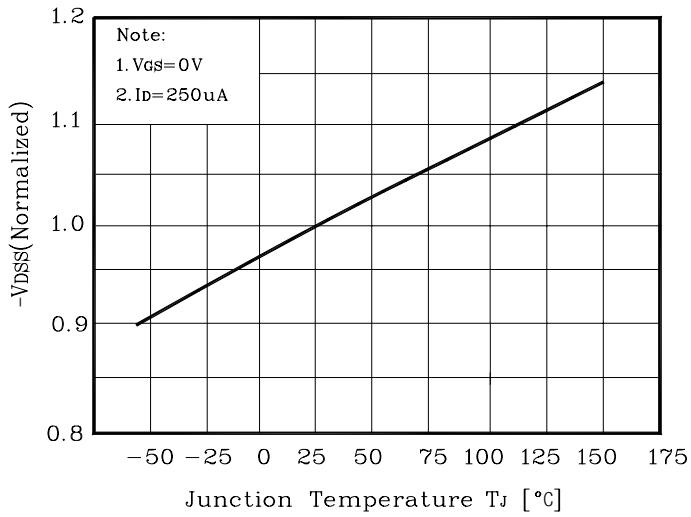


Fig. 8 $R_{DS(on)}$ - T_J

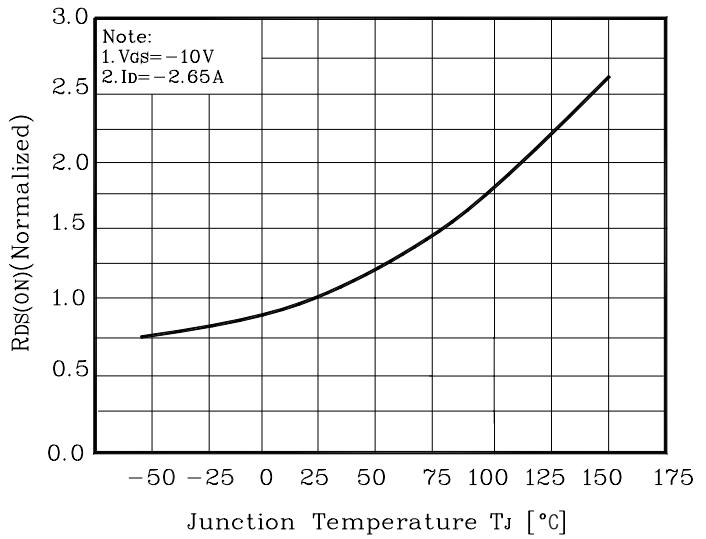


Fig. 9 I_D - T_a

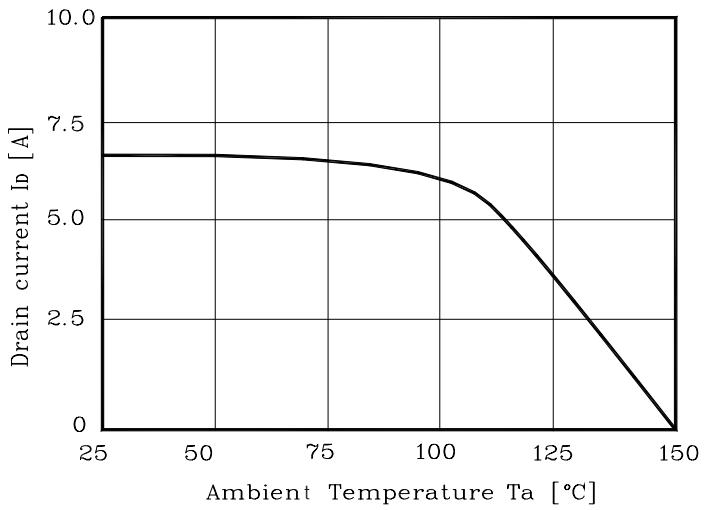


Fig. 10 Safe Operating Area

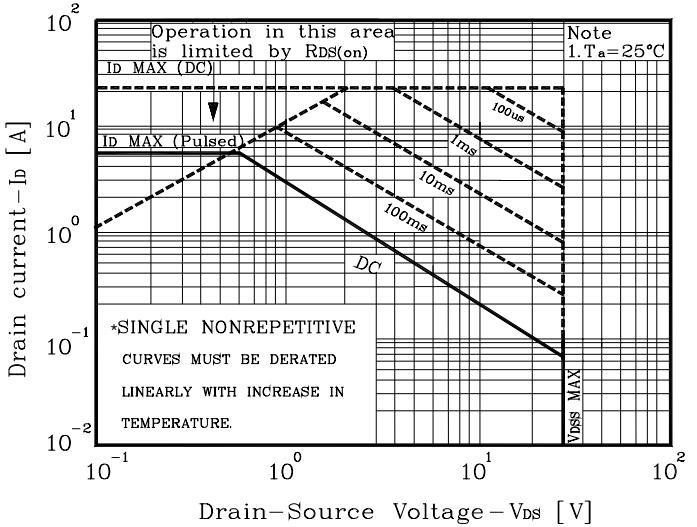


Fig. 11 Gate Charge Test Circuit & Waveform

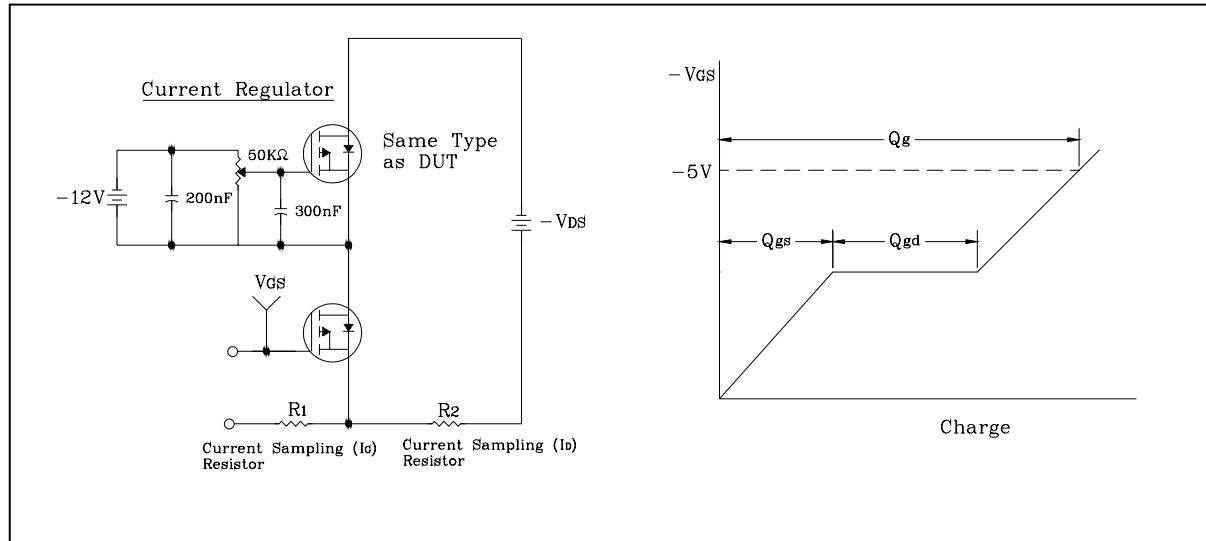


Fig. 12 Resistive Switching Test Circuit & Waveform

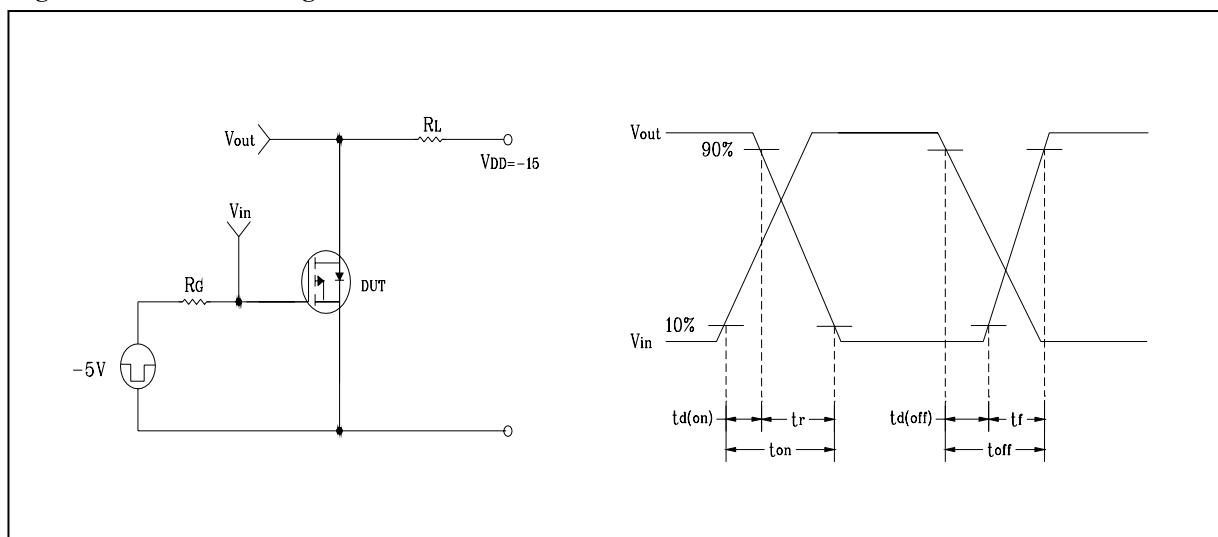


Fig. 13 E_{AS} Test Circuit & Waveform

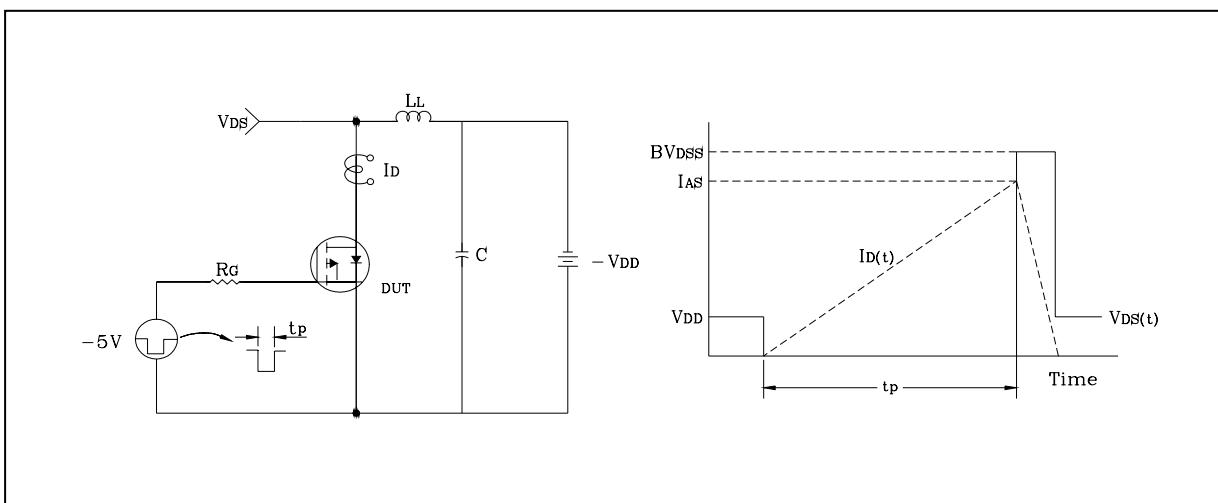
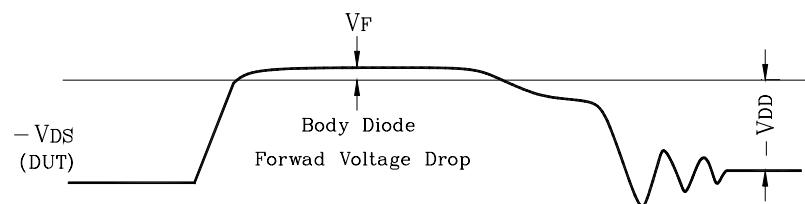
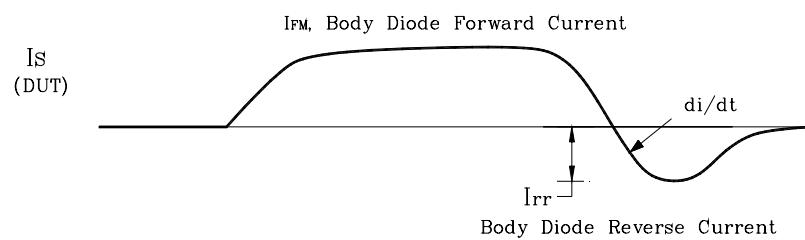
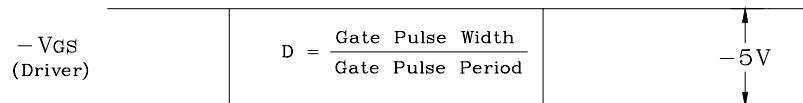
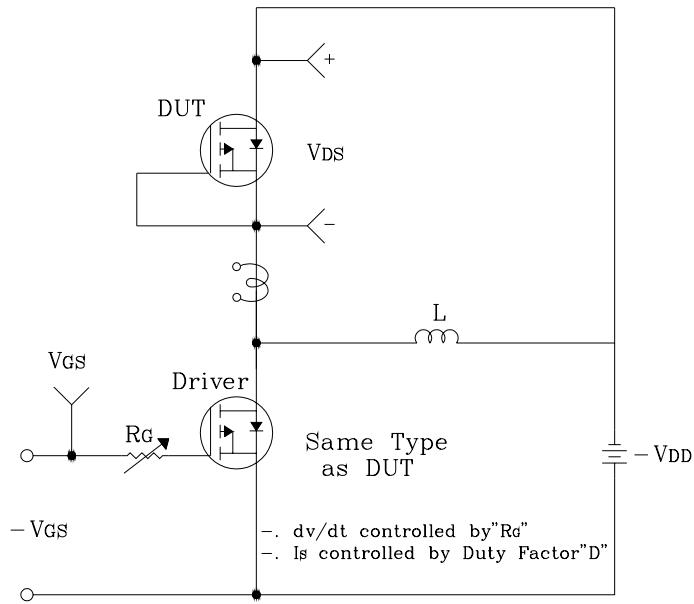


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform



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